

ADS1204

SBAS301A - OCTOBER 2003 - REVISED JUNE 2004

Four 1-Bit, 10MHz, 2nd-Order, **Delta-Sigma Modulators**

FEATURES

- 16-Bit Resolution
- Resolution/Speed Trade-Off: 07250 00 10-Bit Effective D 10-Bit Effective Resolution with 10µs Signal Delay (12-Bit with 19μs)

Burr-Brown Products from Texas Instruments

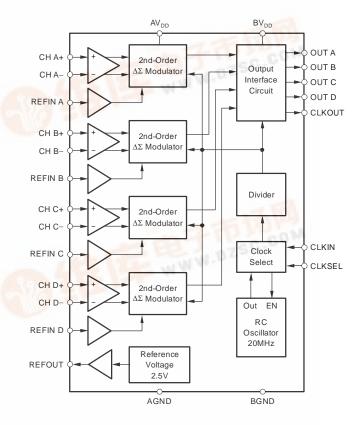
- ±2.5V Input Range at 2.5V
- Internal Reference Voltage: 2%
- Gain Error: 0.5%
- Four Independent Delta-Sigma Modulators
- Four Input Reference Buffers
- **Onboard 20MHz Oscillator**
- Selectable Internal or External Clock
- **Operating Temperature Range:** -40°C to +85°C
- QFN-32 (5x5) Package

APPLICATIONS

- **Motor Control**
- **Current Measurement**
- **Industrial Process Control**
- Instrumentation
- **Smart Transmitters**
- Portable Instruments
- **Weight Scales**
- **Pressure Transducers**

DESCRIPTION

The ADS1204 is a four-channel, high-performance device, with four delta-sigma ($\Delta\Sigma$) modulators with 100dB dynamic range, operating from a single +5V supply. The differential inputs are ideal for direct connection to transducers in an industrial environment. With the appropriate digital filter and modulator rate, the device can be used to achieve 16-bit analog-to-digital (A/D) conversion with no missing code. Effective resolution of 12 bits can be obtained with a digital filter data rate of 160kHz at a modulator rate of 10MHz. The ADS1204 is designed for use in medium- to high-resolution measurement applications including current measurements, smart transmitters, industrial process control, weight scales, chromatography, and portable instrumentation. It is available in a QFN-32 (5x5) package.



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This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

ORDERING INFORMATION

PRODUCT	MAXIMUM INTEGRAL LINEARITY ERROR (LSB)	MAXIMUM GAIN ERROR (%)	PACKAGE- LEAD	PACKAGE DESIGNATOR ⁽¹⁾	SPECIFIED TEMPERATURE RANGE	PACKAGE MARKING	ORDERING NUMBER	TRANSPORT MEDIA, QUANTITY
ADS1204		10.5	OFN 00	DUD	4000 + 0500	A D C 4 C C 4 I	ADS1204IRHBT	Tape and Reel, 250
ADS1204	±3	±0.5	QFN-32	RHB	-40°C to +85°C	ADS1204I	ADS1204IRHBR	Tape and Reel, 3000

⁽¹⁾ For the most current specification and package information, refer to our web site at www.ti.com.

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range unless otherwise noted(1)

	ADS1204	UNIT
Supply Voltage, AV _{DD} to AGND	-0.3 to 6	V
Supply Voltage, BV _{DD} to BGND	-0.3 to 6	V
Analog Input Voltage with Respect to AGND	AGND – 0.3 to AV _{DD} + 0.3	V
Reference Input Voltage with Respect to AGND	AGND – 0.3 to AV _{DD} + 0.3	V
Digital Input Voltage with Respect to BGND	BGND – 0.3 to BV _{DD} + 0.3	V
Ground Voltage Difference, AGND to BGND	±0.3	V
Voltage Differences, BVDD to AGND	-0.3 to 6	V
Input Current to Any Pin Except Supply	±10	mA
Power Dissipation	See Dissipation Rating Table	•
Operating Virtual Junction Temperature Range, TJ	-40 to +150	°C
Operating Free-Air Temperature Range, TA	-40 to +85	°C
Storage Temperature Range, TSTG	-65 to +150	°C
Lead Temperature (1.6mm or 1/16" from case for 10s)	260	°C

⁽¹⁾ Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

RECOMMENDED OPERATING CONDITIONS

PARAMETER		MIN	NOM	MAX	UNIT
Supply Voltage, AV _{DD} to AGND		4.75	5	5.25	V
Cumply Voltage DV to DCND	Low-Voltage Levels	2.7		3.6	V
Supply Voltage, BV _{DD} to BGND	5V Logic Levels	4.5	5	5.5	V
Reference Input Voltage	•	0.5	2.5	2.6	V
Operating Common-Mode Signal		0		AV_{DD}	V
Analog Inputs	+IN - (-IN)	0		±REFIN	V
External Clock(1)	•	16	20	24	MHz
Operating Junction Temperature Range, T		-40		105	°C

⁽¹⁾ With reduced accuracy, clock can go from 1MHz up to 32MHz; see Typical Characteristic curves.

DISSIPATION RATING TABLE

PACKAGE	T _A ≤ 25°C	DERATING FACTOR	T _A = 70°C	T _A = 85°C
	POWER RATING	ABOVE T _A = 25°C(1)	POWER RATING	POWER RATING
QFN-32 (5x5)	2725mW	27.25mW/°C	1499mW	1090mW

⁽¹⁾ This is the inverse of the traditional junction-to-ambient thermal resistance (R_{θJA}). Thermal resistances are not production tested and are for informational purposes only.



ELECTRICAL CHARACTERISTICS

Over recommended operating free-air temperature range at -40° C to $+85^{\circ}$ C, $AV_{DD} = 5V$, $BV_{DD} = 3V$, CH x+ = 0.5V to 4.5V, CH x- = 2.5V, REFIN = REFOUT = internal +2.5V, CLKIN = 20MHz, and 16-bit $Sinc^3$ filter with decimation by 256, unless otherwise noted.

				ADS1204I		
PARAMETER		TEST CONDITIONS	MIN	TYP(1)	MAX	UNITS
Resolution	1		16			Bits
DC Accura	асу	•				
INL	Integral linearity error(2)			±1	±3	LSB
IINL	integral lineality error(2)			±0.001	±0.005	% FSR
	Integral linearity match				6	LSB
	•				0.009	% FSR
DNL	Differential nonlinearity ⁽³⁾				±1	LSB
Vos	Input offset error			-1.4	±3	mV
	Input offset error match				2	mV
TCVOS	Input offset error drift			2	8	μV/°C
GERR	Gain error ⁽⁴⁾	Referenced to V _{REF}		0.08	±0.5	% FSR
	Gain error match			0.185	0.5	% FSR
TCGERR	Gain error drift			2		ppm/°C
PSRR	Power-supply rejection ratio	4.75V < AV _{DD} < 5.25V		78		dB
Analog Inp	out					
FSR	Full-scale differential range	(CH x+) - (CH x-); CH x- = 2.5V			±2.5	V
	Specified differential range	(CH x+) - (CH x-); CH x- = 2.5V			±2	V
	Maximum operating input range(3)		0		AV_{DD}	V
	Input capacitance	Common-mode		3		pF
	Input leakage current	CLK turned off			±1	nA
	Differential input resistance			100		kΩ
	Differential input capacitance			2.5		pF
CMRR	Common mode rejection ratio	At DC		100		dB
CIVIKK	Common-mode rejection ratio	$V_{IN} = \pm 1.25 V_{PP}$ at $40 kHz$		110		dB
BW	Bandwidth	FS sine wave, -3dB		50		MHz
Sampling I	Dynamics					
	Internal clock frequency	CLKSEL = 1	8	10	12	MHz
CLKIN	External clock frequency	CLKSEL = 0	1	20	24	MHz
AC Accura	асу					
THD	Total harmonic distortion	$V_{IN} = \pm 2V_{PP}$ at 5kHz		-96	-88	dB
SFDR	Spurious-free dynamic range	$V_{IN} = \pm 2V_{PP}$ at 5kHz	92	100		dB
SNR	Signal-to-noise ratio	$V_{IN} = \pm 2V_{PP}$ at 5kHz	86	89		dB
SINAD	Signal-to-noise + distortion	V _{IN} = ±2V _{PP} at 5kHz	85	89		dB
	Channel-to-channel isolation(3)	V _{IN} = ±2V _{PP} at 50kHz		85		dB
ENOB	Effective number of bits		14	14.5		Bits

⁽¹⁾ All typical values are at $T_A = +25^{\circ}C$.

⁽²⁾ Integral nonlinearity is defined as the maximum deviation of the line through the end points of the specified input range of the transfer curve for CH x+ = -2V to +2V at 2.5V, expressed either as the number of LSBs or as a percent of measured input range (4V).

⁽³⁾ Ensured by design.

⁽⁴⁾ Maximum values, including temperature drift, are ensured over the full specified temperature range.

⁽⁵⁾ Applicable for 5.0V nominal supply: BV_{DD} (min) = 4.5V and BV_{DD} (max) = 5.5V.

⁽⁶⁾ Applicable for 3.0V nominal supply: BVDD (min) = 2.7V and BVDD (max) = 3.6V.

SBAS301A - OCTOBER 2003 - REVISED JUNE 2004

ELECTRICAL CHARACTERISTICS (continued)

Over recommended operating free-air temperature range at -40° C to $+85^{\circ}$ C, $AV_{DD} = 5V$, $BV_{DD} = 3V$, $CH_{X+} = 0.5V$ to 4.5V, $CH_{X-} = 2.5V$, REFIN = REFOUT = internal +2.5V, CLKIN = 20MHz, and 16-bit Sinc³ filter with decimation by 256, unless otherwise noted.

				ADS1204I		
PARAMETER		TEST CONDITIONS	MIN	TYP(1)	MAX	UNITS
Voltage Reference Output			•			
VOUT	Reference voltage output	-40°C to +85°C	2.450	2.5	2.550	V
dV _{OUT} /dT	Output voltage temperature drift			±20		ppm/°C
	Outrot valtage seine	$f = 0.1Hz$ to $10Hz$, $C_L = 10\mu F$		10		μVrms
	Output voltage noise	$f = 10Hz$ to $10kHz$, $C_L = 10\mu F$		12		μVrms
PSRR	Power-supply rejection ratio			60		dB
lout	Output current			10		μΑ
Isc	Short-circuit current			0.5		mA
	Turn-on settling time	to 0.1% at C _L = 0		100		μs
Voltage Ref	erence Input		<u>.</u>			
VIN	Reference voltage input		0.5	2.5	2.6	V
	Reference input resistance			100		MΩ
	Reference input capacitance			5		pF
	Reference input current				1	μΑ
Digital Inpu	_{ts} (5)					
	Logic family		CMOS w	ith Schmitt	Trigger	
VIH	High-level input voltage		0.7×BV _{DD}		BV _{DD} +0.3	V
VIL	Low-level input voltage		-0.3		0.3×BV _{DD}	V
IN	Input current	V _I = BV _{DD} or GND			±50	nA
Cl	Input capacitance			5		pF
Digital Outp	outs(5)					
	Logic family			CMOS		
Vон	High-level output voltage	$BV_{DD} = 4.5V$, $I_{OH} = -100\mu A$	4.44			V
VOL	Low-level output voltage	$BV_{DD} = 4.5V$, $I_{OL} = +100\mu A$			0.5	V
CO	Output capacitance			5		pF
CL	Load capacitance				30	pF
	Data format			Bit Stream		

⁽¹⁾ All typical values are at $T_A = +25$ °C.

⁽²⁾ Integral nonlinearity is defined as the maximum deviation of the line through the end points of the specified input range of the transfer curve for CH x+ = -2V to +2V at 2.5V, expressed either as the number of LSBs or as a percent of measured input range (4V).

⁽³⁾ Ensured by design.

⁽⁴⁾ Maximum values, including temperature drift, are ensured over the full specified temperature range.

⁽⁵⁾ Applicable for 5.0V nominal supply: BV_{DD} (min) = 4.5V and BV_{DD} (max) = 5.5V. (6) Applicable for 3.0V nominal supply: BV_{DD} (min) = 2.7V and BV_{DD} (max) = 3.6V.



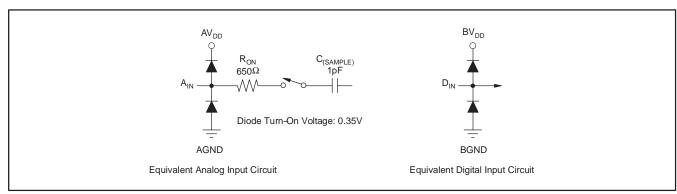
ELECTRICAL CHARACTERISTICS (continued)

Over recommended operating free-air temperature range at -40° C to $+85^{\circ}$ C, AV_{DD} = 5V, BV_{DD} = 3V, CH x+ = 0.5V to 4.5V, CH x- = 2.5V, REFIN = REFOUT = internal +2.5V, CLKIN = 20MHz, and 16-bit Sinc³ filter with decimation by 256, unless otherwise noted.

				ADS1204I		
PARAME	TER	TEST CONDITIONS	MIN	TYP(1)	MAX	UNITS
Digital In	puts(6)	-	1			
	Logic family			LVCMOS		
٧ıH	High-level input Voltage	BV _{DD} = 3.6V	2		BV _{DD} +0.3	V
V _{IL}	Low-level input voltage	BV _{DD} = 2.7V	-0.3		0.8	V
I _{IN}	Input current	$V_I = BV_{DD}$ or GND			±50	nA
Cl	Input capacitance			5		pF
Digital O	utputs(6)					
	Logic family			LVCMOS		
VOH	High-level output voltage	$BV_{DD} = 2.7V$, $I_{OH} = -100\mu A$	BV _{DD} -0.2			V
VOL	Low-level output voltage	$BV_{DD} = 2.7V$, $I_{OL} = +100\mu A$			0.2	V
CO	Output capacitance			5		pF
CL	Load capacitance				30	pF
	Data format			Bit Stream		
Power St	upply					
AV_{DD}	Analog supply voltage		4.5		5.5	V
D\/	Duffer I/O avent visite as	Low-voltage levels	2.7		3.6	V
BV_{DD}	Buffer I/O supply voltage	5V logic levels	4.5		5.5	V
۸۱	Analog operating supply current	CLKSEL = 1		22.5	30	mA
AI_{DD}	Analog operating supply current	CLKSEL = 0		22.4	29	mA
DI	Duffer I/O energting cumply current	BV _{DD} = 3V, CLKOUT = 10MHz			4	mA
BIDD	Buffer I/O operating supply current	BV _{DD} = 5V, CLKOUT = 10MHz			4	mA
	Dower discination	CLKSEL = 0		122	145	mW
	Power dissipation	CLKSEL = 1		112.5	150	mW

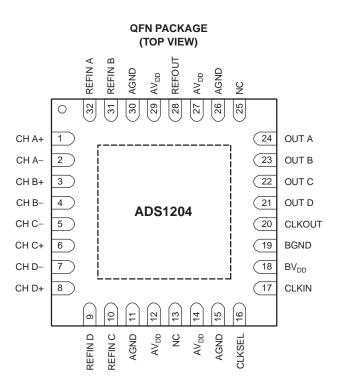
- (1) All typical values are at $T_A = +25$ °C.
- (2) Integral nonlinearity is defined as the maximum deviation of the line through the end points of the specified input range of the transfer curve for CH x+ = -2V to +2V at 2.5V, expressed either as the number of LSBs or as a percent of measured input range (4V).
- (3) Ensured by design.
- (4) Maximum values, including temperature drift, are ensured over the full specified temperature range.
- (5) Applicable for 5.0V nominal supply: BV_{DD} (min) = 4.5V and BV_{DD} (max) = 5.5V.
- (6) Applicable for 3.0V nominal supply: BV_{DD} (min) = 2.7V and BV_{DD} (max) = 3.6V.

EQUIVALENT INPUT CIRCUIT





PIN ASSIGNMENTS



Terminal Functions

TERMINAL			
NAME NO.		I/O	DESCRIPTION
CH A+	1	AI	Analog input of channel A: noninverting input
CH A-	2	AI	Analog input of channel A: inverting input
CH B+	3	AI	Analog input of channel B: noninverting input
CH B-	4	AI	Analog input of channel B: inverting input
CH C-	5	AI	Analog input of channel C: inverting input
CH C+	6	AI	Analog input of channel C: noninverting input
CH D-	7	AI	Analog input of channel D: inverting input
CH D+	8	AI	Analog input of channel D: noninverting input
REFIN D	9	Al	Reference voltage input of channel D: pin for external reference voltage
REFIN C	10	Al	Reference voltage input of channel C: pin for external reference voltage
AGND	11		Analog ground
AV_{DD}	12	Р	Analog power supply; nominal 5V
NC	13		No connection; this pin is left unconnected
AV_{DD}	14	Р	Analog power supply; nominal 5V
AGND	15		Analog ground
CLKSEL	16	I	Clock select between internal clock (CLKSEL = 1) or external clock (CLKSEL = 0)

TERMINAL			
NAME NO.		I/O	DESCRIPTION
CLKIN	17	I	External clock input
BV _{DD}	18	Р	Digital interface power supply; from 2.7V to 5.5V
BGND	19		Interface ground
CLKOUT	20	0	System clock output
OUT D	21	0	Bit stream from channel D modulator
OUT C	22	0	Bit stream from channel C modulator
OUT B	23	0	Bit stream from channel B modulator
OUT A	24	0	Bit stream from channel A modulator
NC	25		No connection; this pin is left unconnected
AGND	26		Analog ground
AV _{DD}	27	Р	Analog power supply; nominal 5V
REFOUT	28	AO	Reference voltage output: output pin of the internal reference source; nominal 2.5V
AV_{DD}	29	Р	Analog power supply; nominal 5V
AGND	30		Analog ground
REFIN B	31	Al	Reference voltage input of channel B: pin for external reference voltage
REFIN A	32	AI	Reference voltage input of channel A: pin for external reference voltage

NOTE: AI = Analog Input; AO = Analog Output; I = Input; O = Output; P = Power Supply.



PARAMETER MEASUREMENT INFORMATION

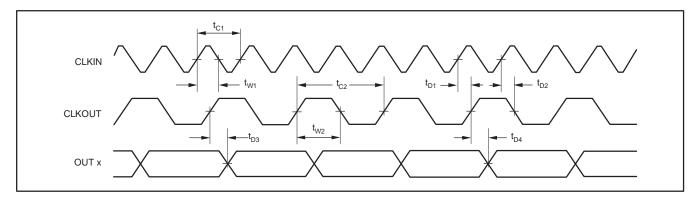


Figure 1. ADS1204 Timing Diagram

TIMING REQUIREMENTS: 5.0V

over recommended operating free-air temperature range at -40° C to $+85^{\circ}$ C, AV_{DD} = 5V, and BV_{DD} = 5V, unless otherwise noted.

PARAMI	ETER	MIN	MAX	UNIT
tC1	CLKIN period	41.6	1000	ns
t _{W1}	CLKIN high time	10	t _{C1} – 10	ns
tC2	CLKOUT period using internal oscillator (CLKSEL = 1)	83	125	ns
	CLKOUT period using external clock (CLKSEL = 0)	2×tC1		ns
t _{W2}	CLKOUT high time	$(t_{C2}/2) - 5$	$(t_{C2}/2) + 5$	ns
t _{D1}	CLKOUT rising edge delay after CLKIN rising edge	0	10	ns
t _{D2}	CLKOUT falling edge delay after CLKIN rising edge	0	10	ns
t _{D3}	Data valid delay after rising edge of CLKOUT (CLKSEL = 1)	$(t_{C2}/4) - 8$	$(t_{C2}/4) + 8$	ns
t _{D4}	Data valid delay after rising edge of CLKOUT (CLKSEL = 0)	t _{W1} – 3	t _{W1} + 7	ns

NOTE: Applicable for 5.0V nominal supply: BV_{DD} (min) = 4.5V and BV_{DD} (max) = 5.5V. All input signals are specified with $t_R = t_F = 5$ ns (10% to 90% of BV_{DD}) and timed from a voltage level of $(V_{IL} + V_{IH})/2$. See timing diagram.

TIMING REQUIREMENTS: 3.0V

over recommended operating free-air temperature range at -40° C to $+85^{\circ}$ C, AV_{DD} = 5V, and BV_{DD} = 3V, unless otherwise noted.

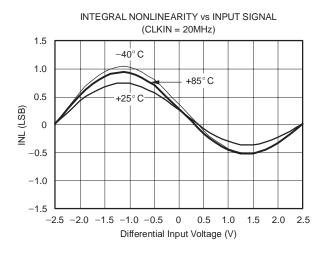
PARAMET	ER	MIN	MAX	UNIT
tC1	CLKIN period	41.6	1000	ns
t _{W1}	CLKIN high time	10	t _{C1} – 10	ns
t _{C2}	CLKOUT period using internal oscillator (CLKSEL = 1)	83	125	ns
	CLKOUT period using external clock (CLKSEL = 0)	$2 \times t_{C1}$		ns
t _{W2}	CLKOUT high time	$(t_{C2}/2) - 5$	$(t_{C2}/2) + 5$	ns
^t D1	CLKOUT rising edge delay after CLKIN rising edge	0	10	ns
t _{D2}	CLKOUT falling edge delay after CLKIN rising edge	0	10	ns
t _{D3}	Data valid delay after rising edge of CLKOUT (CLKSEL = 1)	$(t_{C2}/4) - 8$	$(t_{C2}/4) + 8$	ns
t _{D4}	Data valid delay after rising edge of CLKOUT (CLKSEL = 0)	t _{W1} – 3	t _{W1} + 7	ns

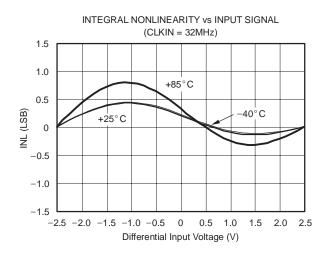
NOTE: Applicable for 3.0V nominal supply: BV_{DD} (min) = 2.7V and BV_{DD} (max) = 3.6V. All input signals are specified with $t_R = t_F = 5$ ns (10% to 90% of BV_{DD}) and timed from a voltage level of $(V_{IL} + V_{IH})/2$. See timing diagram.

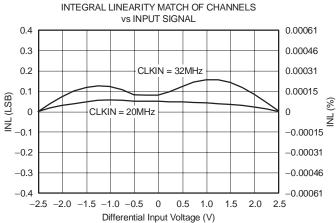


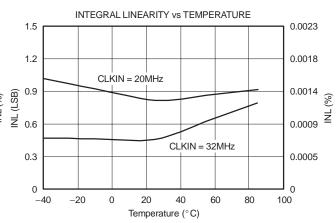
TYPICAL CHARACTERISTICS

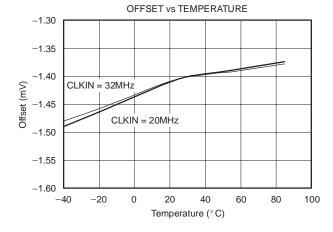
 $AV_{DD} = 5V$, $BV_{DD} = 3V$, CH x+ = +0.5V to +4.5V, CH x- = +2.5V, REFIN = external, CLKSEL = 0, and 16-bit $Sinc^3$ filter, with OSR = 256, unless otherwise noted.

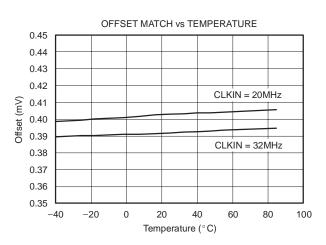








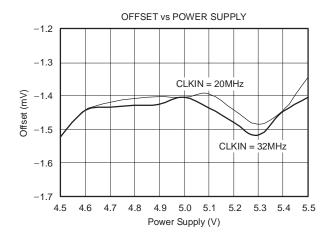


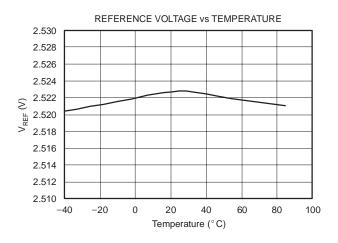


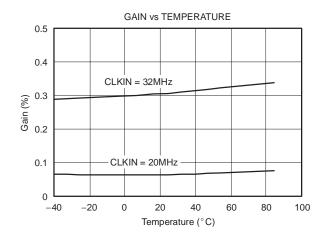


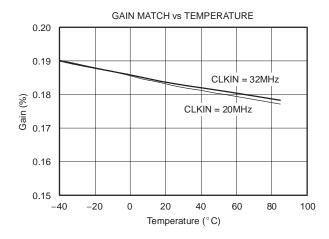
TYPICAL CHARACTERISTICS (continued)

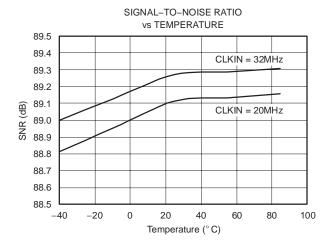
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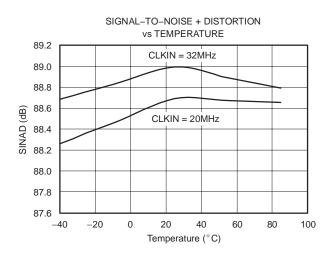








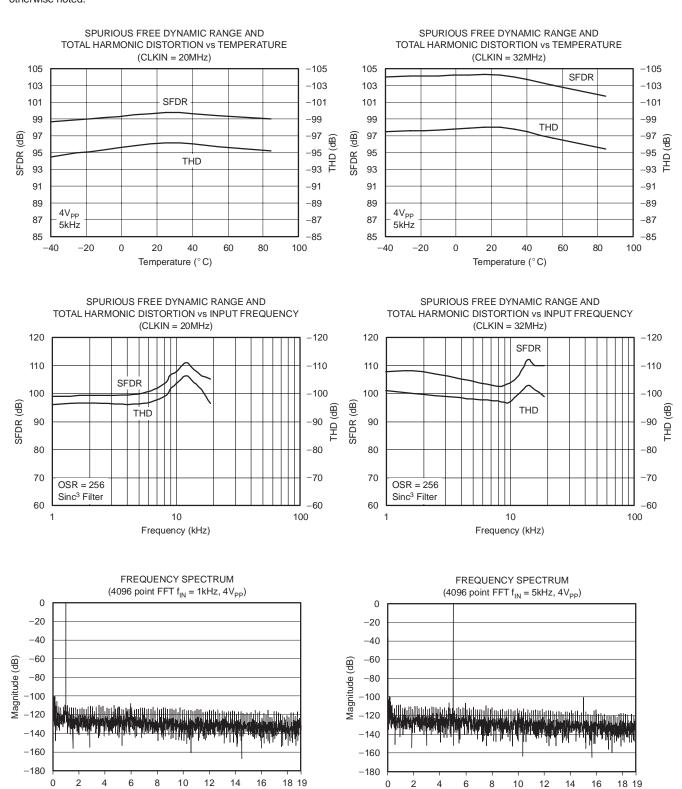






TYPICAL CHARACTERISTICS (continued)

 $AV_{DD} = 5V$, $BV_{DD} = 3V$, CH x+ = +0.5V to +4.5V, CH x- = +2.5V, REFIN = external, CLKSEL = 0, and 16-bit $Sinc^3$ filter, with OSR = 256, unless otherwise noted.



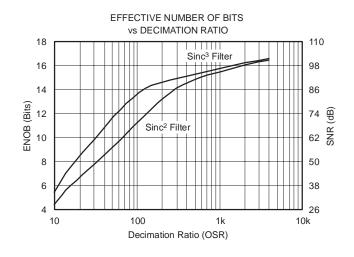
Frequency (kHz)

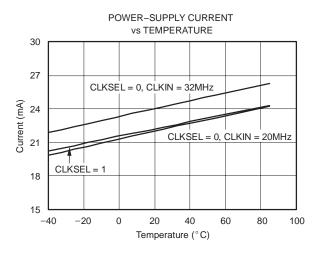
Frequency (kHz)

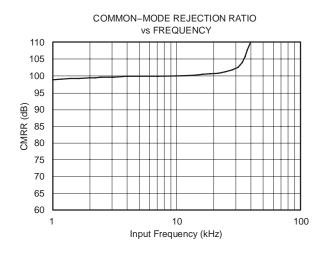


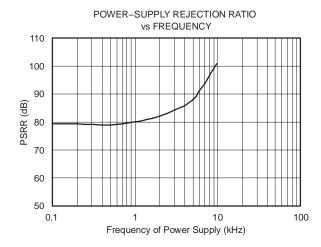
TYPICAL CHARACTERISTICS (continued)

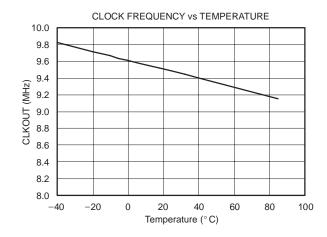
 $AV_{DD} = 5V$, $BV_{DD} = 3V$, CH x+ = +0.5V to +4.5V, CH x- = +2.5V, REFIN = external, CLKSEL = 0, and 16-bit $Sinc^3$ filter, with OSR = 256, unless otherwise noted.

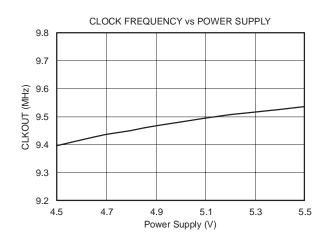














GENERAL DESCRIPTION

The ADS1204 is a four-channel, 2nd-order, CMOS device with four delta-sigma modulators, designed for medium- to high-resolution A/D signal conversions from DC to 39kHz (filter response –3dB) if an oversampling ratio (OSR) of 64 is chosen. The output of the converter (OUT $_{\rm X}$) provides a stream of digital ones and zeros. The time average of this serial output is proportional to the analog input voltage.

The modulator shifts the quantization noise to high frequencies. A low-pass digital filter should be used at the output of the delta-sigma modulator. The filter serves two functions. First, it filters out high-frequency noise. Second, the filter converts the 1-bit data stream at a high sampling rate into a higher-bit data word at a lower rate (decimation).

An application-specific integrated circuit (ASIC), or field-programmable gate array (FPGA) could be used to implement the digital filter. Figure 2 and Figure 3 show typical application circuits with the ADS1204 connected to an FPGA.

The overall performance (that is, speed and accuracy) depends on the selection of an appropriate OSR and filter type. A higher OSR produces greater output accuracy while operating at a lower refresh rate. Alternatively, a lower OSR produces lower output accuracy, but operates at a higher refresh rate. This system allows flexibility with the digital filter design and is capable of A/D conversion results that have a dynamic range exceeding 100dB with an OSR = 256.

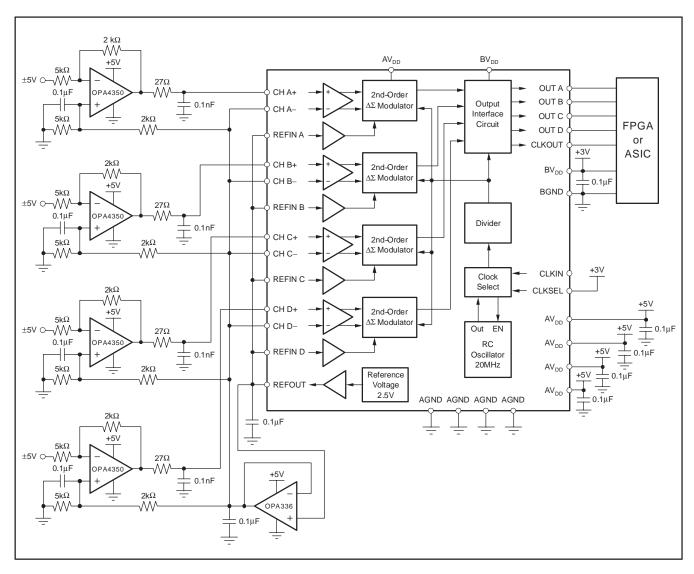


Figure 2. Single-Ended Connection Diagram for the ADS1204 Delta-Sigma Modulator



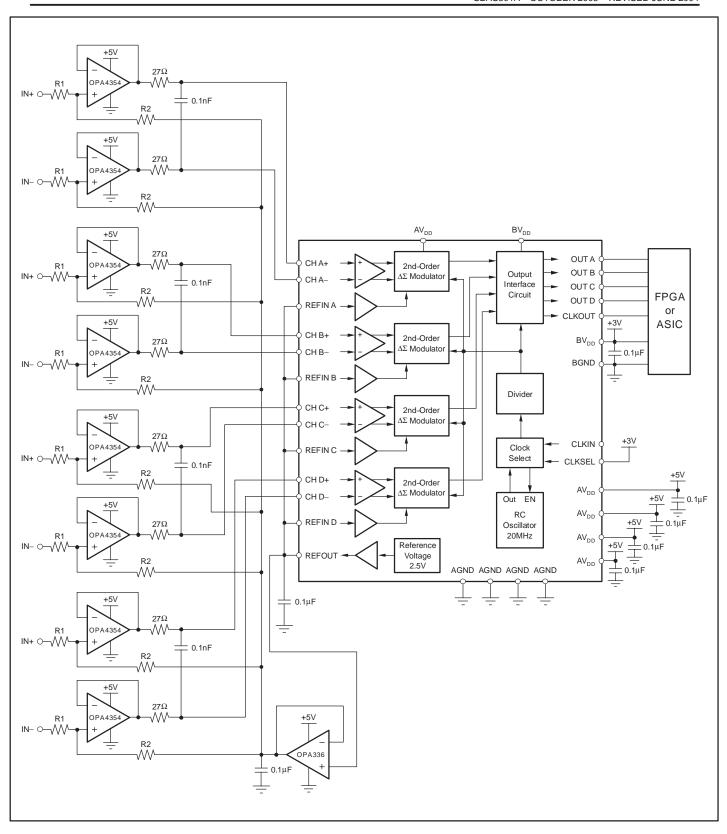


Figure 3. Differential Connection Diagram for the ADS1204 Delta-Sigma Modulator



THEORY OF OPERATION

The differential analog input of the ADS1204 is implemented with a switched-capacitor circuit. This circuit implements a 2nd-order modulator stage, which digitizes the analog input signal into a 1-bit output stream. The clock source can be internal as well as external. Different frequencies for this clock allow for a variety of solutions and signal bandwidths. Every analog input signal is continuously sampled by the modulator and compared to a reference voltage that is applied to the REFINx pin. A digital stream, which accurately represents the analog input voltage over time, appears at the output of the corresponding converter.

ANALOG INPUT STAGE

Analog Input

The topology of the analog inputs of ADS1204 is based on fully differential switched–capacitor architecture. This input stage provides the mechanism to achieve low system noise, high common-mode rejection (100dB), and excellent power-supply rejection.

The input impedance of the analog input is dependent on the modulator clock frequency (f_{CLK}), which is also the sampling frequency of the modulator. Figure 4 shows the basic input structure of one channel of the ADS1204. The relationship between the input impedance of the ADS1204 and the modulator clock frequency is:

$$Z_{IN} = \frac{100k\Omega}{f_{MOD}/10MHz} \tag{1}$$

The input impedance becomes a consideration in designs where the source impedance of the input signal is high. This high impedance may cause degradation in gain, linearity, and THD. The importance of this effect depends

on the desired system performance. There are two restrictions on the analog input signals, CH x+ and CH x-. If the input voltage exceeds the range (GND - 0.3V) to (VDD + 0.3V), the input current must be limited to 10mA because the input protection diodes on the front end of the converter will begin to turn on. In addition, the linearity and the noise performance of the device is ensured only when the differential analog voltage resides within $\pm 2V$ (with VREF as a midpoint); however, the FSR input voltage is $\pm 2.5V$.

Modulator

The ADS1204 can be operated in two modes. When CKLSEL = 1, the four modulators operate using the internal clock, which is fixed at 20MHz. When CKLSEL = 0, the modulators operate using an external clock . In both modes, the clock is divided by two internally and functions as the modulator clock. The frequency of the external clock can vary from 1MHz to 32MHz to adjust for the clock requirements of the application.

The modulator topology is fundamentally a 2nd-order, switched-capacitor, delta-sigma modulator, such as the one conceptualized in Figure 5. The analog input voltage and the output of the 1-bit digital-to-analog converter (DAC) are differentiated, providing analog voltages at X2 and X3. The voltages at X2 and X3 are presented to their individual integrators. The output of these integrators progresses in a negative or positive direction. When the value of the signal at X4 equals the comparator reference voltage, the output of the comparator switches from negative to positive, or positive to negative, depending on its original state. When the output value of the comparator switches from high to low or vice versa, the 1-bit DAC responds on the next clock pulse by changing its analog output voltage at X6, causing the integrators to progress in the opposite direction. The feedback of the modulator to the front end of the integrators forces the value of the integrator output to track the average of the input.

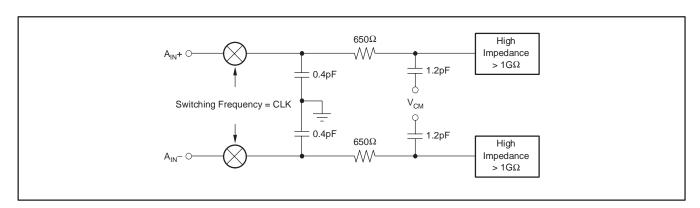


Figure 4. Input Impedance of the ADS1204



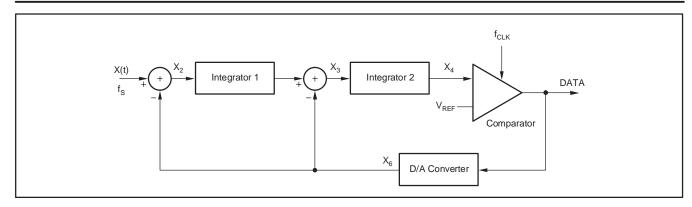


Figure 5. Block Diagram of the 2nd-Order Modulator

DIGITAL OUTPUT

A differential input signal of 0V will ideally produce a stream of ones and zeros that are high 50% of the time and low 50% of the time. A differential input of +2V produces a stream of ones and zeros that are high 80% of the time. A differential input of -2V produces a stream of ones and zeros that are high 20% of the time. The input voltage versus the output modulator signal is shown in Figure 6.

DIGITAL INTERFACE

INTRODUCTION

The analog signal connected to the input of the delta-sigma modulator is converted using the clock signal applied to the modulator. The result of the conversion, or modulation, is generated and sent to the OUTx pin from the delta-sigma modulator. In most applications where a direct

connection is realized between the delta-sigma modulator and an ASIC or FPGA (each with an implemented filter), the two standard signals per modulator (CLKOUT and OUTx) are provided from the modulator. The output clock signal is equal for all four modulators. If CLKSEL = 1, CLKIN must always be set either high or low.

MODES OF OPERATION

The system clock of the ADS1204 is 20MHz by default. The system clock can be provided either from the internal 20MHz RC oscillator or from an external clock source. For this purpose, the CLKIN pin is provided; it is controlled by the mode setting, CLKSEL.

The system clock is divided by two for the modulator clock. Therefore, the default clock frequency of the modulator is 10MHz. With a possible external clock range of 1MHz to 32MHz, the modulator operates between 500kHz and 16MHz.

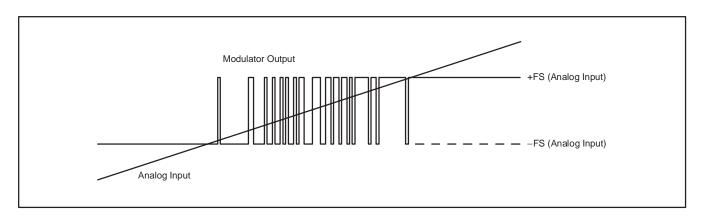


Figure 6. Analog Input vs Modulator Output of the ADS1204



FILTER USAGE

The modulator generates only a bitstream, which does not output a digital word like an A/D converter. In order to output a digital word equivalent to the analog input voltage, the bitstream must be processed by a digital filter.

A very simple filter, built with minimal effort and hardware, is the Sinc³ filter:

$$H(z) = \left(\frac{1 - z^{-OSR}}{1 - z^{-1}}\right)^{3}$$
 (2)

This filter provides the best output performance at the lowest hardware size (for example, a count of digital gates). For oversampling ratios in the range of 16 to 256, this is a good choice. All the characterizations in the data sheet are also done using a Sinc³ filter with an oversampling ratio of OSR = 256 and an output word width of 16 bits.

In a Sinc³ filter response (shown in Figure 7 and Figure 8), the location of the first notch occurs at the frequency of output data rate $f_{DATA} = f_{CLK}/OSR$. The -3dB point is located at half the Nyquist frequency or $f_{DATA}/4$. For some applications, it may be necessary to use another filter type for better frequency response.

This performance can be improved, for example, by a cascaded filter structure. The first decimation stage can be a Sinc³ filter with a low OSR and the second stage a high-order filter.

For more information, see application note SBAA094, Combining the ADS1202 with an FPGA Digital Filter for Current Measurement in Motor Control Applications, available for download at www.ti.com.

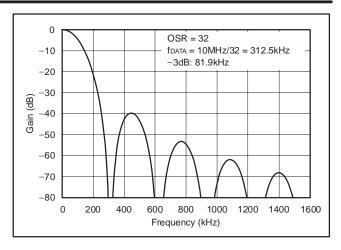


Figure 7. Frequency Response of Sinc³ Filter

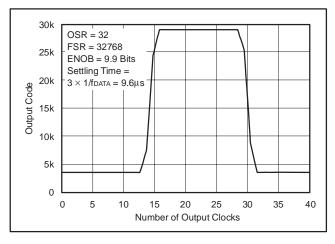


Figure 8. Pulse Response of Sinc³ Filter (f_{MOD} = 10MHz)



The effective number of bits (ENOB) can be used to compare the performance of ADCs and delta-sigma modulators. Figure 9 shows the ENOB of the ADS1204 with different filter types. In this data sheet, the ENOB is calculated from the SNR:

$$SNR = 1.76dB + 6.02dB \times ENOB$$
 (3)

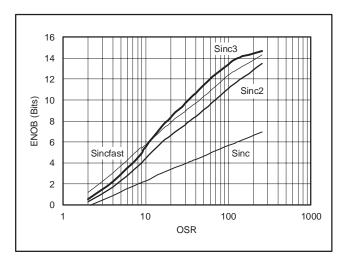


Figure 9. Measured ENOB vs OSR

In motor control applications, a very fast response time for overcurrent detection is required. There is a constraint between $1\mu s$ and $5\mu s$ with 3 bits to 7 bits resolution. The time for full settling is dependent on the filter order. Therefore, the full settling of the Sinc³ filter needs three data clocks and the Sinc² filter needs two

data clocks. The data clock is equal to the modulator clock divided by the OSR. For overcurrent protection, filter types other than Sinc^3 might be a better choice. A simple example is a Sinc^2 filter. Figure 10 compares the settling time of different filter types. The Sincfast is a modified Sinc^2 filter:

$$H(z) = \left(\frac{1 - z^{-OSR}}{1 - z^{-1}}\right)^{2} (1 + z^{-2 \times OSR})$$
(4)

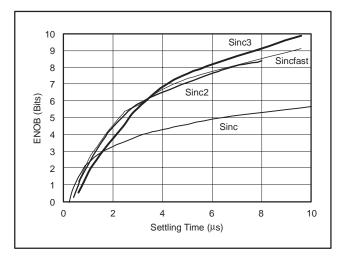


Figure 10. Measured ENOB vs Settling Time

For more information, see application note SBAA094, Combining the ADS1202 with an FPGA Digital Filter for Current Measurement in Motor Control Applications, available for download at www.ti.com.



LAYOUT CONSIDERATIONS

POWER SUPPLIES

An applied external digital filter rejects high-frequency noise. PSRR and CMRR improve at higher frequencies because the digital filter suppresses high-frequency noise.

However, the suppression of the filter is not infinite, so high-frequency noise still influences the conversion result. Inputs to the ADS1204, such as CH x+, CH x-, and CLKIN, should not be present before the power supply is on. Violating this condition could cause latch-up. If these signals are present before the supply is on, series resistors should be used to limit the input current to a maximum of 10mA. Experimentation may be the best way to determine the appropriate connection between the ADS1204 and different power supplies.

GROUNDING

Analog and digital sections of the design must be carefully and cleanly partitioned. Each section should have its own ground plane with no overlap between them. Do not join the ground planes; instead, connect the two with a moderate signal trace underneath the converter. However, for different applications with DSPs and switching power supplies, this process might be different.

For multiple converters, connect the two ground planes as close as possible to one central location for all of the converters. In some cases, experimentation may be required to find the best point to connect the two planes together.

DECOUPLING

Good decoupling practices must be used for the ADS1204 and for all components in the design. All decoupling capacitors, specifically the $0.1\mu F$ ceramic capacitors, must be placed as close as possible to the pin being decoupled. A $1\mu F$ and $10\mu F$ capacitor, in parallel with the $0.1\mu F$ ceramic capacitor, can be used to decouple AV_{DD} to AGND as well as BV_{DD} to BGND. At least one $0.1\mu F$ ceramic capacitor must be used to decouple every AV_{DD} to AGND and BV_{DD} to BGND, as well as for the digital supply on each digital component.

The digital supply sets the I/O voltage for the interface and can be set within a range of 2.7V to 5.5V.

In cases where both the analog and digital I/O supplies share the same supply source, an RC filter of 10Ω and $0.1\mu F$ can be used to help reduce the noise in the analog supply.



PACKAGE OPTION ADDENDUM

28-Jun-2004

PACKAGING INFORMATION

ORDERABLE DEVICE	STATUS(1)	PACKAGE TYPE	PACKAGE DRAWING	PINS	PACKAGE QTY
ADS1204IRHBR	ACTIVE	QFN	RHB	32	3000
ADS1204IRHBT	ACTIVE	QFN	RHB	32	250

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs. **LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

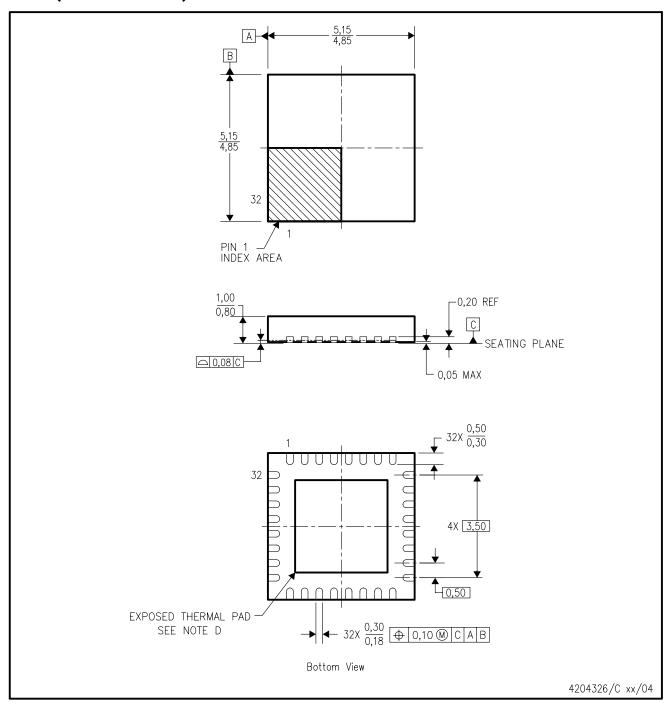
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

RHB (S-PQFP-N32)

PLASTIC QUAD FLATPACK



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. QFN (Quad Flatpack No-Lead) Package configuration.
- D The Package thermal pad must be soldered to the board for thermal and mechanical performance. See product data sheet for details regarding the exposed thermal pad dimensions.
- E. Falls within JEDEC MO-220.



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